



Title of Change:	Quality improvement for applications using LMV358 devices at low temperature (-40C).		
Effective date:	16 February 2016		
Contact information:	Contact your local ON Semiconductor Sales Office or <Shannon.riggs@onsemi.com>		
Type of notification:	ON Semiconductor will consider this change accepted.		
Change category:	<input type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input checked="" type="checkbox"/> Other		
Change Sub-Category(s):	<input type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Manufacturing Process Change	<input type="checkbox"/> Material Change <input checked="" type="checkbox"/> Product specific change	<input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____
Sites Affected:	<input type="checkbox"/> All site(s) <input checked="" type="checkbox"/> not applicable <input type="checkbox"/> ON Semiconductor site(s) :	<input type="checkbox"/> External Foundry/Subcon site(s)	
Description and Purpose:	ON Semiconductor is making a quality improvement adjustment on the LMV358 product line to reduce product sensitivity to process & temperature variation. This improvement will correct a cold temperature (-40C) VCM jitter issue identified during bench evaluation. There is no change to datasheet specifications or electrical characterization. This change will be present on all future wafer lots processed after W1, 2016.		
List of Affected Standard Parts:	LMV358DR2G LMV358DMR2G LMV358MUTAG		